

## -30V P-Channel Enhancement Mode MOSFET

### Description

The AP190P03P/T uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

### General Features

$V_{DS} = -30V$   $I_D = -190A$

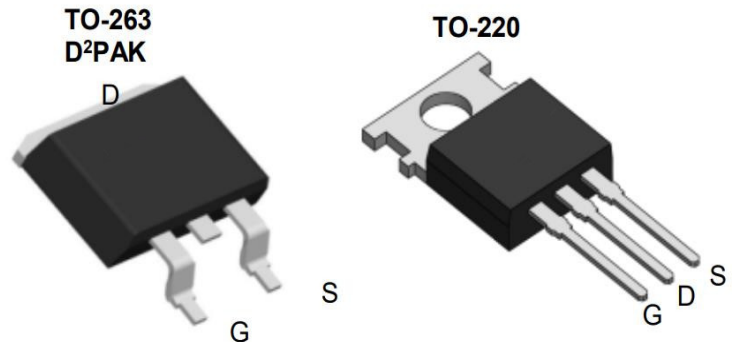
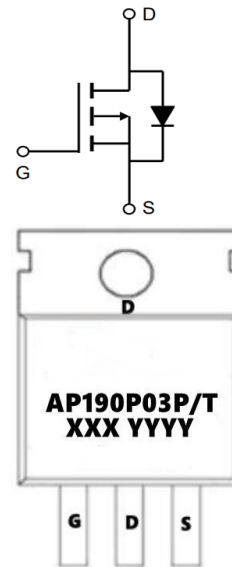
$R_{DS(ON)} < 3.2m\Omega @ V_{GS} = -10V$  (Type: 2.5m $\Omega$ )

### Application

Lithium battery protection

Wireless impact

Mobile phone fast charging



### Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP190P03P	TO-220-3L	AP190P03P XXX YYYY	1000
AP190P03T	TO-263-3L	AP190P03T XXX YYYY	800

### Absolute Maximum Ratings (TC=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	-30	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D@TC=25°C</sub>	Continuous Drain Current, V <sub>GS</sub> @ -10V <sub>1</sub>	-190	A
I <sub>D@TC=100°C</sub>	Continuous Drain Current, V <sub>GS</sub> @ -10V <sub>1</sub>	-125	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	-700	A
E <sub>AS</sub>	Single Pulse Avalanche Energy <sup>3</sup>	876	mJ
I <sub>AS</sub>	Avalanche Current	-70	A
P <sub>D@TC=25°C</sub>	Total Power Dissipation <sup>4</sup>	150	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>	62.5	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	1.06	°C/W



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### Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

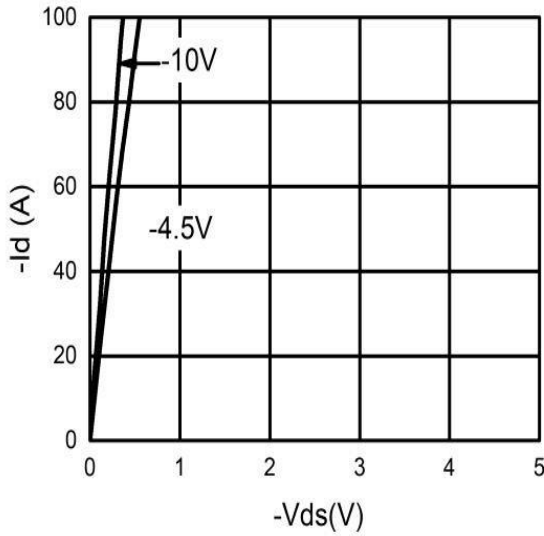
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
BVDSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V I <sub>D</sub> =-250μA	-30	-35		V
IDSS	Zero Gate Voltage Drain Current	V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V			-1	μA
IGSS	Gate-Body Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V			±100	nA
VGS(th)	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-1	-1.7	-2.5	V
RDS(ON)	Drain-Source On-State Resistance	V <sub>GS</sub> =-10V, I <sub>D</sub> =-20A		2.5	3.2	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-20A		4.0	5.2	mΩ
gFS	Forward Transconductance	V <sub>DS</sub> =-5V, I <sub>D</sub> =-20A		65		S
Ciss	Input Capacitance	V <sub>DS</sub> =-15V, V <sub>GS</sub> =0V, f=1.0MHz		7000		pF
Coss	Output Capacitance			820		pF
Crss	Reverse Transfer Capacitance			540		pF
Rg	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1.0MHz		2.2		Ω
td(on)	Turn-on Delay Time	V <sub>GS</sub> =-10V, V <sub>DS</sub> =-15V, R <sub>L</sub> =0.75Ω, R <sub>GEN</sub> =3Ω		14		nS
t <sub>r</sub>	Turn-on Rise Time			13		nS
td(off)	Turn-Off Delay Time			65		nS
t <sub>f</sub>	Turn-Off Fall Time			37		nS
Q <sub>g</sub>	Total Gate Charge	V <sub>GS</sub> =-10V, V <sub>DS</sub> =-15V, I <sub>D</sub> =-20A		130		nC
Q <sub>gs</sub>	Gate-Source Charge			12		nC
Q <sub>gd</sub>	Gate-Drain Charge			31		nC
ISD	Source-Drain Current (Body Diode)				-150	A
VSD	Forward on Voltage <sup>(Note 3)</sup>	V <sub>GS</sub> =0V, I <sub>S</sub> =-20A			-1.3	V
trr	Reverse Recovery Time	I <sub>F</sub> =-20A, di/dt=100A/μs		30		ns
Q <sub>rr</sub>	Reverse Recovery Charge	I <sub>F</sub> =-20A, di/dt=100A/μs		40		nC

#### Note :

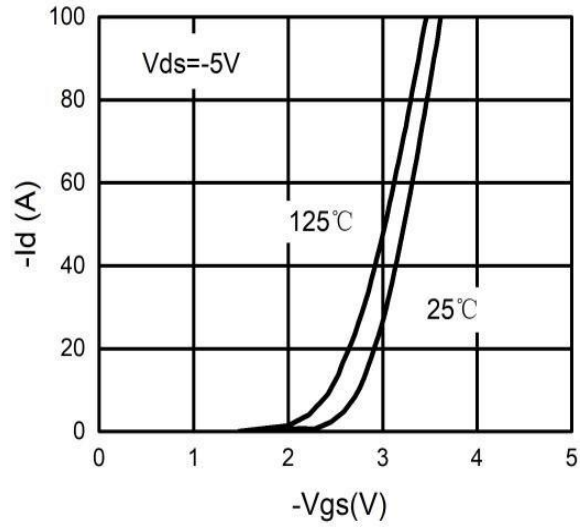
- 1、 The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、 The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3、 The EAS data shows Max. rating . The test condition is T<sub>J</sub> =25°C, V<sub>DD</sub>=-15V, V<sub>G</sub>=-10V, R<sub>G</sub>=25Ω, L=0.5mH, I<sub>AS</sub>=-30A
- 4、 The power dissipation is limited by 150°C junction temperature
- 5、 The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.

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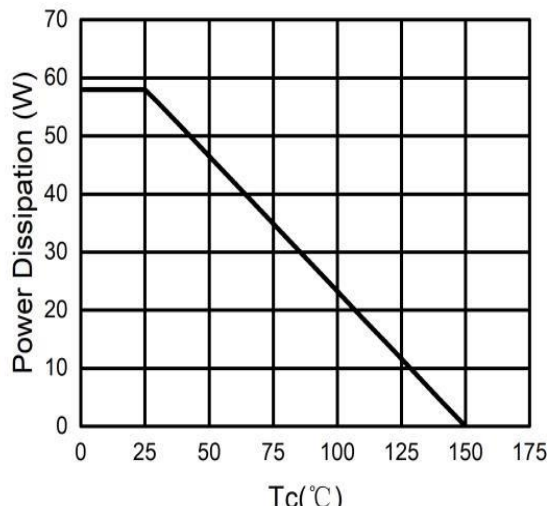
**Typical Characteristics**



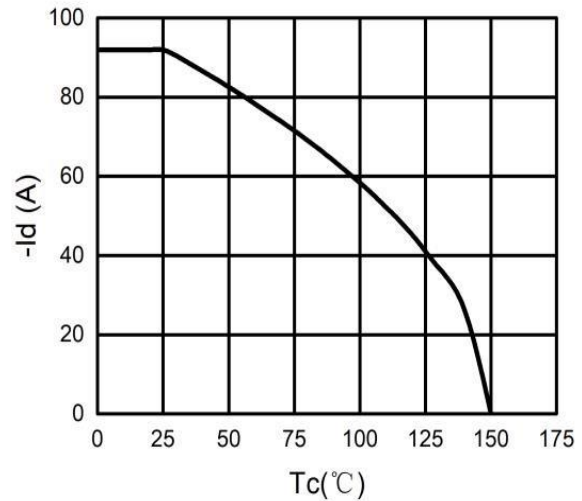
**Figure 1. Output Characteristics**



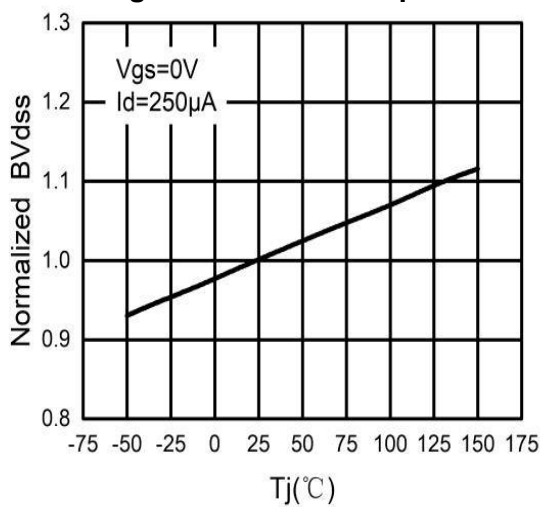
**Figure 2. Transfer Characteristics**



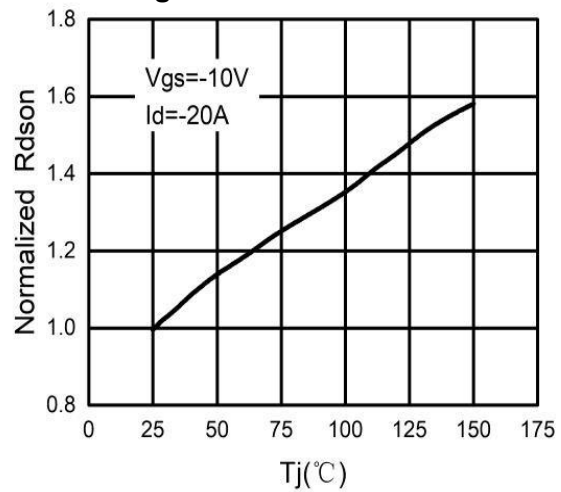
**Figure 3. Power Dissipation**



**Figure 4. Drain Current**

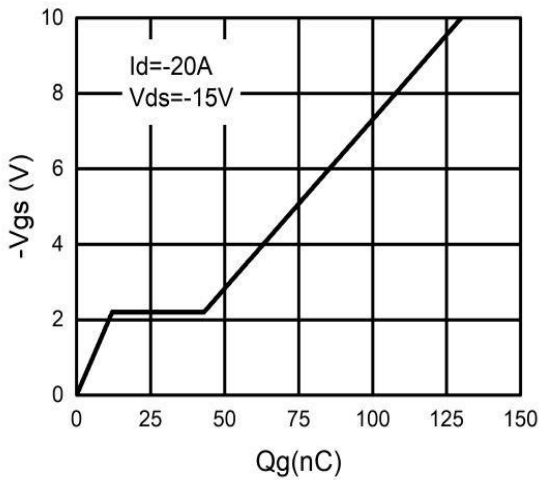


**Figure 5.  $BV_{DSS}$  vs Junction Temperature**

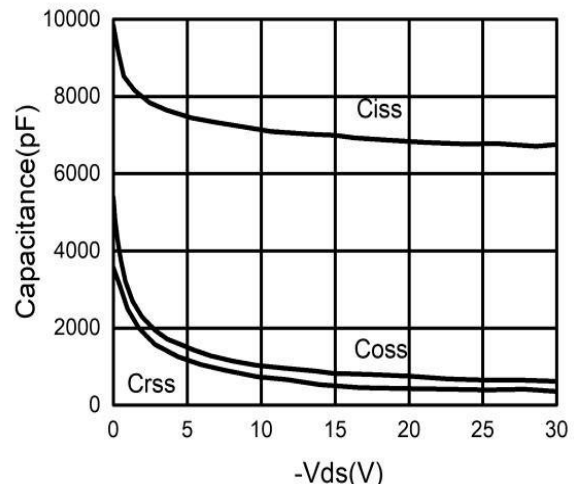


**Figure 6.  $R_{DS(ON)}$  vs Junction Temperature**

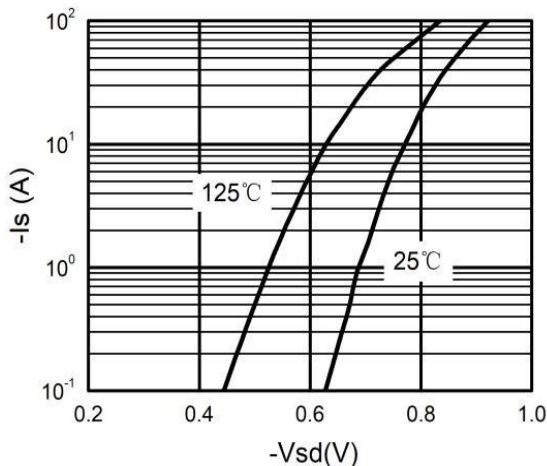
**-30V P-Channel Enhancement Mode MOSFET**



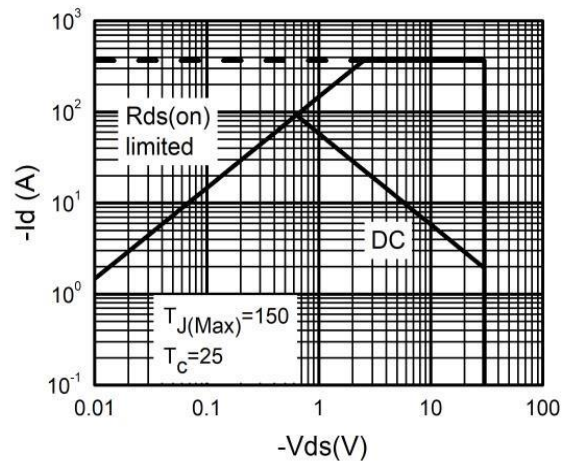
**Figure 7. Gate Charge Waveforms**



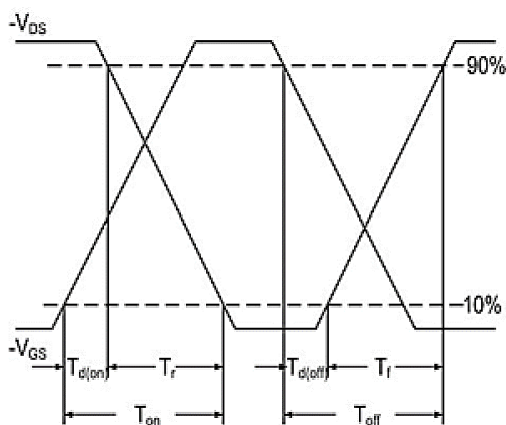
**Figure 8. Capacitance**



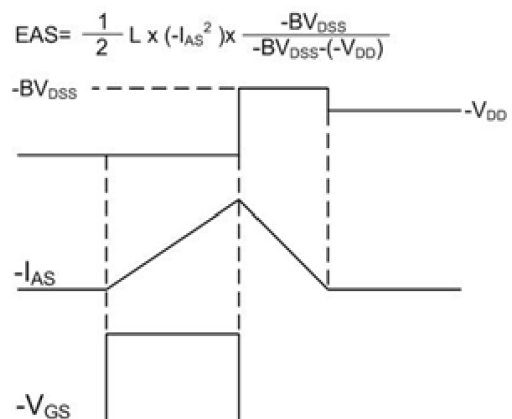
**Figure 9. Body-Diode Characteristics**



**Figure 10. Maximum Safe Operating Area**



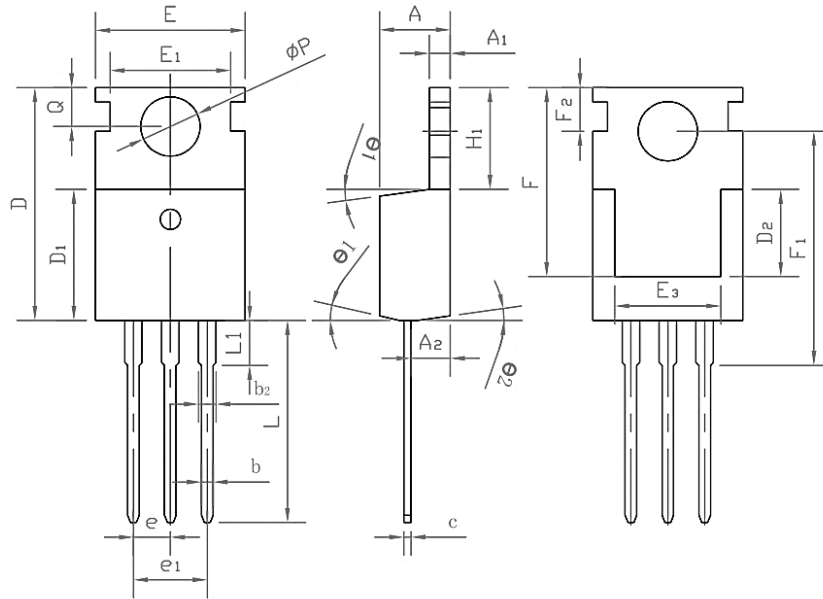
**Figure.11 Switching Time Waveform**



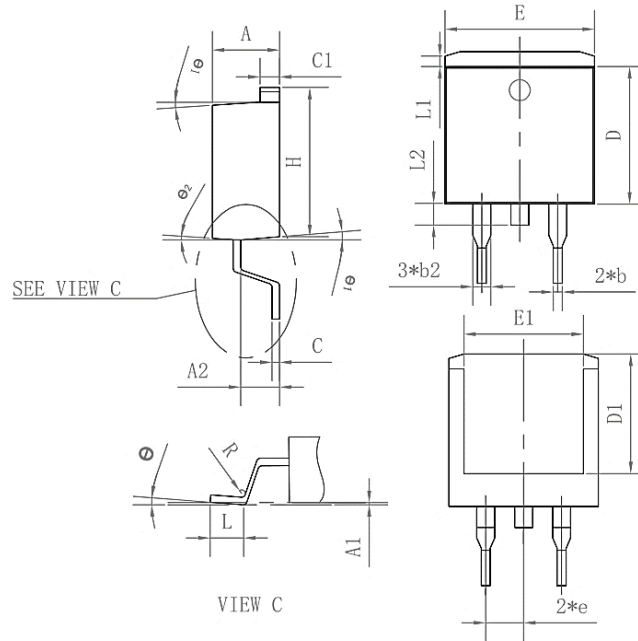
**Figure.12 Unclamped Inductive Switching Waveform**

## -30V P-Channel Enhancement Mode MOSFET

### Package Mechanical Data-TO-220-3L-SLK



Symbol	Common		
	mm		
	Mim	Nom	Max
A	4.27	4.57	4.87
A1	1.15	1.30	1.45
A2	2.10	2.40	2.70
b	0.70	0.80	1.00
b2	1.17	1.27	1.50
D	0.40	0.50	0.65
D1	8.80	9.10	9.40
D2	5.70	6.70	7.00
E	9.70	10.00	10.30
E1	-	8.70	-
E2	9.63	10.00	10.35
E3	7.00	8.00	8.40
e		0.37	
e1		0.10	
H1	6.00	6.50	6.85
L	12.75	13.50	13.90
L1	-	3.10	3.40
$\Phi p$	3.45	3.60	3.75
Q	2.60	2.80	3.00
$\theta_1$	4°	7°	10°
$\theta_2$	0°	3°	6°
F	13.30	13.50	13.70
F1	15.50	15.90	16.30
F2	2.80	3.00	3.20

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**Package Mechanical Data-TO-263-3L-SLK**


Symbol	Common		
	mm		
	Mim	Nom	Max
A	4.35	4.47	4.60
A1	0.09	0.10	0.11
A2	2.30	2.40	2.70
b	0.70	0.80	1.00
b2	1.25	1.36	1.50
C	0.45	0.50	0.65
C1	1.29	1.30	9.40
D	9.10	9.20	9.30
D1	7.90	8.00	8.10
E	9.85	10.00	10.20
E1	7.90	8.00	8.10
H	15.30	15.50	15.70
e	-	2.54	-
L	2.34	2.54	2.74
L1	1.00	1.10	1.20
L2	1.30	1.40	1.50
R	0.24	0.25	0.26
θ	0°	4°	8°
θ1	4°	7°	10°
θ2	0°	3°	6°